### Nch 40V 45A Power MOSFET

V <sub>DSS</sub>	40V
R <sub>DS(on)</sub> (Max.)	13.5mΩ
I <sub>D</sub>	±45A
$P_D$	50W

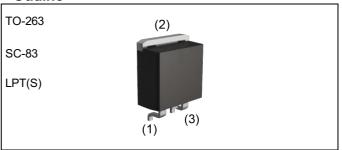
# Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) High power small mold package
- 4) Pb-free lead plating; RoHS compliant.
- 5) AEC-Q101 Qualified

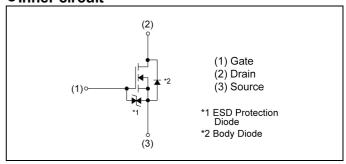
# Application

Switching

### Outline



# •Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TL
	Marking	RSJ451N04

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	40	V
Continuous drain current	I <sub>D</sub> *1	±45	Α
Pulsed drain current	I <sub>DP</sub> *2	±90	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Power dissipation	P <sub>D</sub> *1	50	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Doromotor	Cumbal	Values			Llmit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	1	2.5	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymahal	Conditions		Values		l leit
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = 1 \text{mA}$ referenced to 25°C		46.8	-	mV/°C
Zero gate voltage drain current $I_{DSS}$ $V_{DS} = 40V, V_{GS} = 0V$		V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1	μА
Gate - Source leakage current	Gate - Source leakage current $I_{GSS}$ $V_{GS} = \pm 20$		-	-	±10	μA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V , I <sub>D</sub> = 1mA	1.2	-	3.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta  V_{GS(th)}}{\Delta  T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.9	-	mV/°C
Static drain - source on - state resistance	R <sub>DS(on)</sub> *3	V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A	-	9.5	13.5	mΩ
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	3.2	-	Ω
Forward Transfer $ Y_{fs} ^{*3}$ $V_{DS} = 10V$ ,		V <sub>DS</sub> = 10V, I <sub>D</sub> = 25A	10	-	-	S

<sup>\*1</sup> Tc=25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw≦10µs, Duty cycle≦1%

<sup>\*3</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cyronh ol	Conditions	Values			l lait	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2400	-		
Output capacitance	tput capacitance C <sub>oss</sub>		-	380	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	170	-		
Turn - on delay time	t <sub>d(on)</sub> *3	$V_{DD} \simeq 25V, V_{GS} = 10V$	1	25	-		
Rise time	t <sub>r</sub> *3	I <sub>D</sub> = 25A	-	225	-	no	
Turn - off delay time	t <sub>d(off)</sub> *3	$R_L \simeq 1.0\Omega$	-	90	-	ns	
Fall time	t <sub>f</sub> *3	$R_G = 10\Omega$	-	390	-		

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Parameter	Cymah al	Conditions	Values			Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q <sub>g</sub> *3	V <sub>DD</sub> ≃ 25V.	-	43	-	
Gate - Source charge	Q <sub>gs</sub> *3	V <sub>DD</sub> ≃ 25V, I <sub>D</sub> = 45A,	-	12	-	nC
Gate - Drain charge	Q <sub>gd</sub> *3	V <sub>GS</sub> = 10V	-	6	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			l leit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	40	Α
Pulse forward current	I <sub>SP</sub> *2	⊤ <sub>a</sub> = 25°C	-	-	90	Α
Forward voltage	V <sub>SD</sub> *3	V <sub>GS</sub> = 0V, I <sub>S</sub> = 25A	-	-	1.2	V

Fig.1 Power Dissipation Derating Curve

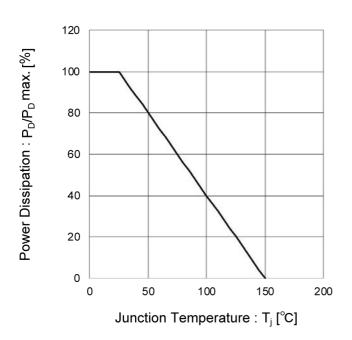
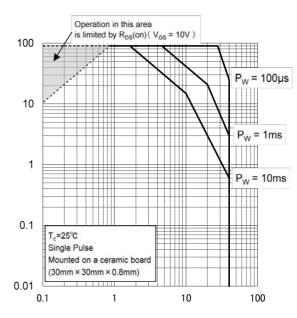


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

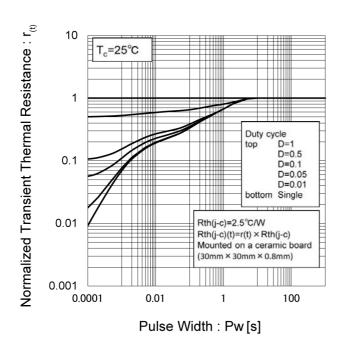


Fig.4 Single Pulse Maximum Power dissipation

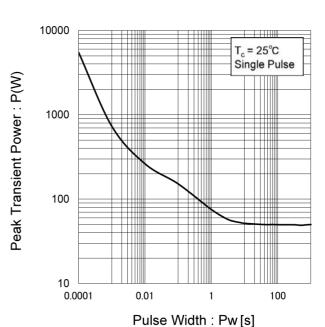


Fig.5 Typical Output Characteristics(I)

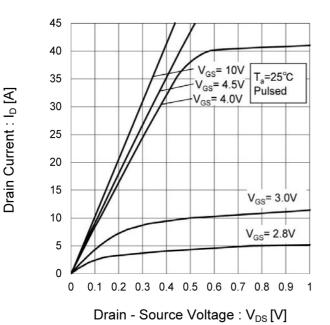
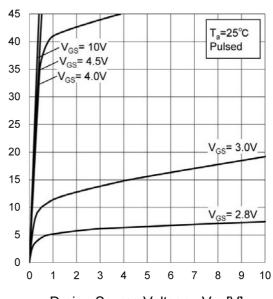


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs. Junction Temperature

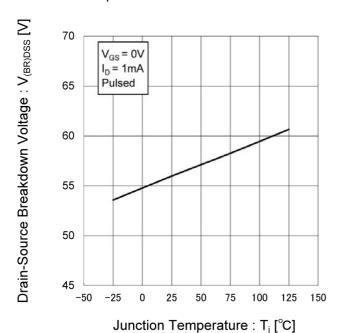


Fig.8 Typical Transfer Characteristics

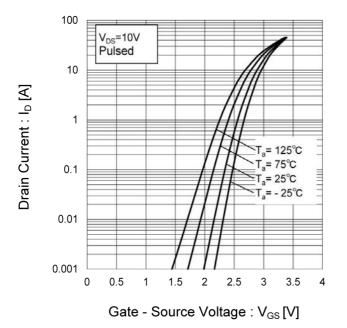


Fig.9 Gate Threshold Voltage vs. Junction Temperature

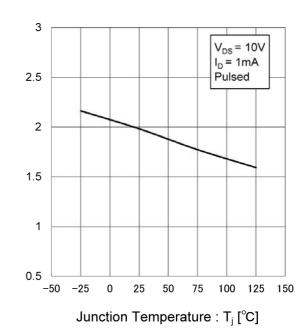
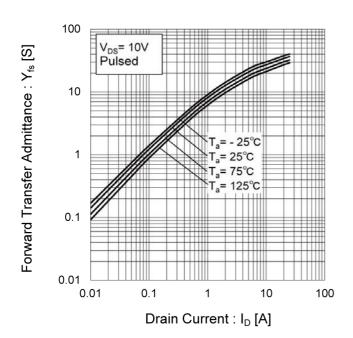


Fig.10 Forward Transfer Admittance vs.
Drain Current



Gate Threshold Voltage: VGS(th) [V]

RSJ451N04FRA

# • Electrical characteristic curves

Fig.11 Drain Current Derating Curve

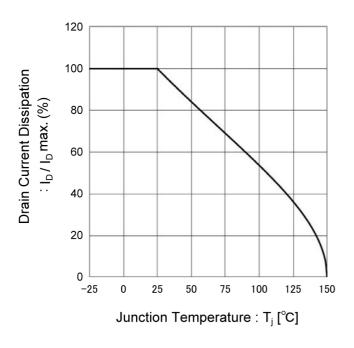


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

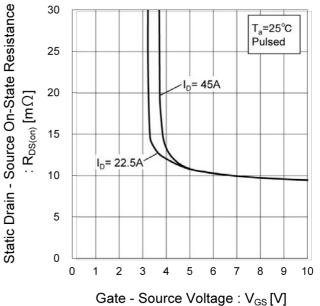




Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

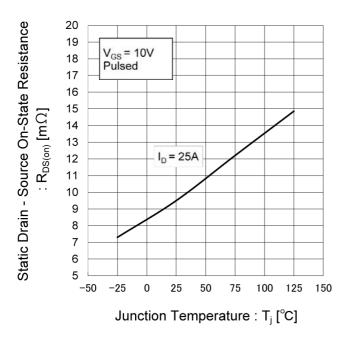


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

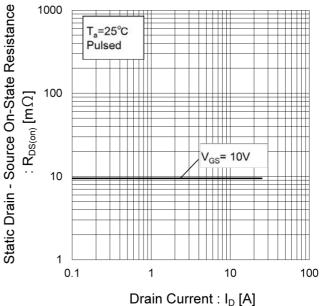
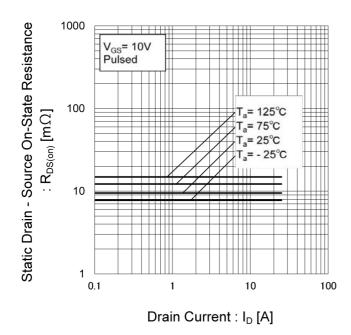


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)



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Fig.16 Typical Capacitance vs. Drain - Source Voltage

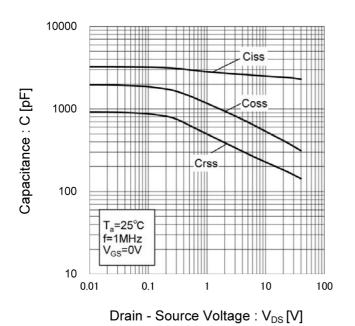


Fig.17 Switching Characteristics

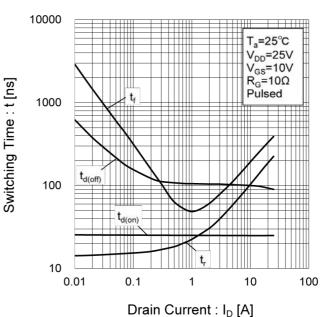


Fig.18 Dynamic Input Characteristics

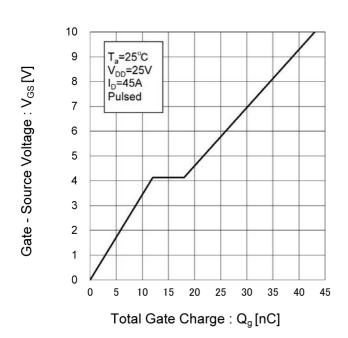
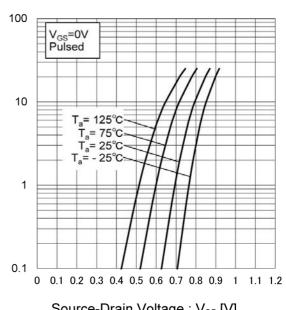


Fig.19 Source Current vs. Source Drain Voltage



Source Current : Is [A]

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### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

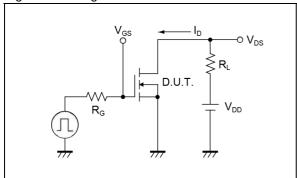


Fig.2-1 Gate Charge Measurement Circuit

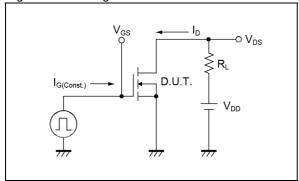


Fig.1-2 Switching Waveforms

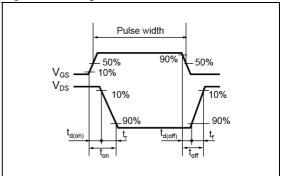
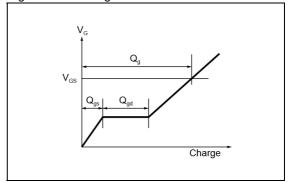
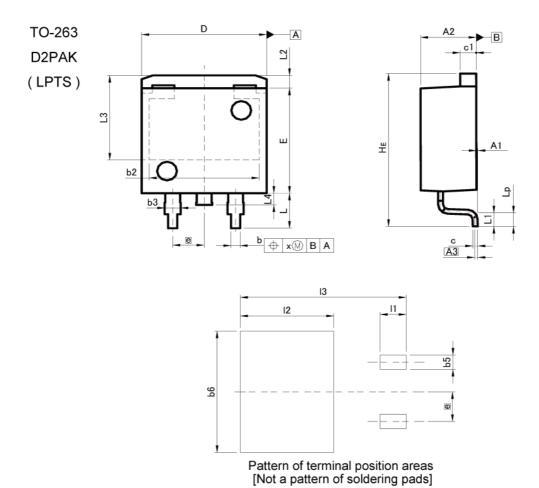


Fig.2-2 Gate Charge Waveform



# Dimensions



DIM MILIM		MILIMETERS		HES	
100000000000000000000000000000000000000	MIN	MAX	MIN	MAX	
A1	0.00	0.30	0.000	0.012	
A2	4.30	4.70	0.169	0.185	
A3	0.:	25	0.0	10	
b	0.68	0.98	0.027	0.039	
b2	8.9	90	0.3	50	
b3	1.14	1.44	0.045	0.057	
С	0.30	0.60	0.012	0.024	
c1	1,10	1.50	0.043	0.059	
D	9.80	10.40	0.386	0.409	
E	8.80	9.20	0.346	0.362	
е	2.	54	0.1	00	
HE	12.80	13.40	0.504	0.528	
L	2.70	3.30	0.106	0.130	
L1	1.	20	0.047		
L2	1.	10	0.0	43	
L3	7.25		0.2	85	
L4	1,0	1.00		39	
Lp	0.90	1.50	0.035	0.059	
X	-	0.25	-	0.010	

MAX

1.23 10.40

- 2.10 - 7.55 - 13.40 Dimension in mm/inches

MIN

**MILIMETERS** 



**INCHES** 

MIN

MAX 0.049

0.409

DIM

bb

b6

11 12 13

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(1.1010.1) Micarda: Equipment Glacomication of the operation (pp.104)								
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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSⅢ					
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII					

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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